





Reflow Soldering System



RF 300 Inline

System Features

- Each heating zone is independently programmable and easily controlled through the on-board TOUCH SCREEN controller
- Reflow profiling capability with on-board programming and ability to add three (3) thermocouples for specific board locations
- Maximum flexibility in defining a reflow profile with conveyor speed, heating temperature, convection heat flow, and cooling fans all easily programmed through the system controller
- Plenum convection heating technology provides uniform temperature profiling across entire PCB board for enhanced SMT process control

Specifications	RF 300
Max. PCB Width	250 mm (10")
Max. PCB Height	35 mm (1.375")
Heating Zones	3 top, 3 bottom
Max Temperature	320°C (608°F)
Heated Tunnel Length	850 mm (34")
Convection	Plenum design
Conveyor	Mesh belt
Conveyor Extensions	
Exhaust	Two (2) 102 mm (4") dia. 250 CFM (425 mm ³ /hr)
Cooling Station(s)	One (1)
Cooling Zone Fans	One (1)
Nitrogen Option	Optional
PC Interface	Included : RS232
Heater (Peak) Power	5.5 kw
Power Requirements	410 VAC, 50/60 Hz, 3 phase
Length	1400 mm (55")
Width	755 mm (30")
Height	450 mm (17.8")

- System's maximum temperature of 320°C is compatible with most lead and lead-free solder paste profiles
- · Clamshell hood design with mechanical strut
- Low mass stainless steel conveyor for board transport
- Store up to 100 individual profiles
- Password protection
- ISO 9000 SPC fault monitoring reporting
- Real time graphic temperature
- Status light tower
- PCB edge pin conveyor available to replace wire mesh conveyor (Optional)







